Chicsp N,

a scrub mark analyzer;

an imaging apparatus configured and operative to obtain images of first scrub marks made by probe card pins on a check plate in said probe card analyzer and images of second scrub marks made by said probe card pins on bonding pads in said scrub mark analyzer; and

a data processor coupled to said imaging apparatus and configured and operative to obtain scrub mark data associated with said first scrub marks and scrub pattern data associated with said second scrub marks and to analyze said scrub mark data and said scrub pattern data; wherein said data processor allows prediction of the behavior of a probe pin on a semiconductor die metalization pad.